

## MM74HC589 8-Bit Shift Registers with Input Latches and 3-STATE Serial Output

### General Description

The MM74HC589 high speed shift register utilizes advanced silicon-gate CMOS technology to achieve the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads.

The MM74HC589 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Data can also be entered serially the shift register through the SER pin. Both the storage register and shift register have positive-edge triggered clocks, RCK and SCK, respectively. SLOAD pin controls parallel LOAD or serial shift operations for the shift register. The shift register has a 3-STATE output to enable the wire-ORing of multiple devices on a serial bus.

The 74HC logic family is speed, function, and pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### Features

- 8-bit parallel storage register inputs
- Wide operating voltage range: 2V–6V
- Shift register has direct overriding load
- Guaranteed shift frequency. . . DC to 30 MHz
- Low quiescent current: 80  $\mu$ A maximum (74HC Series)
- 3-STATE output for 'Wire-OR'

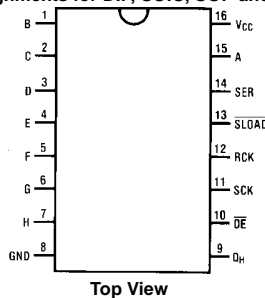
### Ordering Code:

Order Number	Package Number	Package Description
MM74HC589M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC589SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC589MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC589N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Connection Diagram

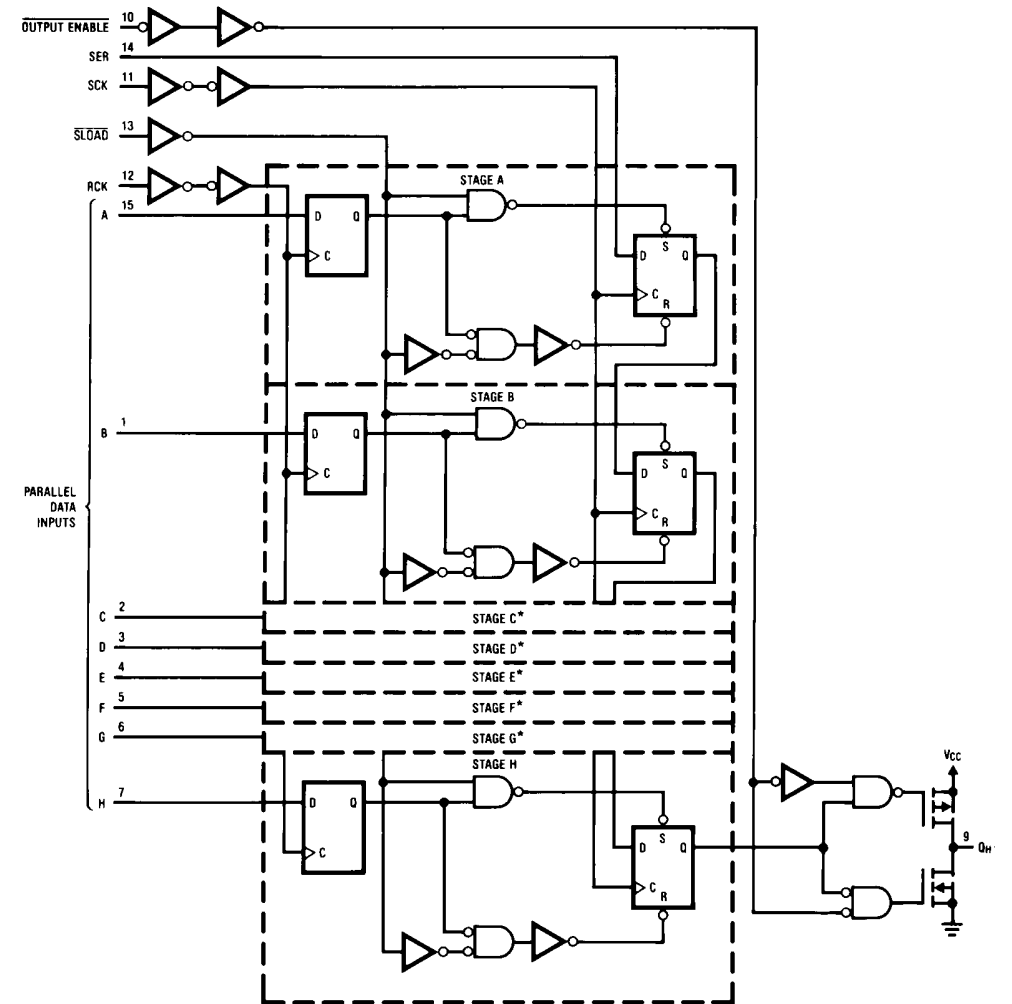
Pin Assignments for DIP, SOIC, SOP and TSSOP



### Truth Table

RCK	SCK	SLOAD	$\overline{OE}$	Function
X	X	X	H	$Q_H$ in Hi-Z State
X	X	X	L	$Q_H$ is enabled
$\uparrow$	X	X	X	Data loaded into input latches
$\uparrow$	X	L	X	Data loaded into shift register from pins
H or L	X	L	X	Data loaded from latches to shift register
X	$\uparrow$	H	X	Shift register is shifted. Data on SER pin is shifted in.
$\uparrow$	$\uparrow$	H	X	Data is shifted in shift register, and data is loaded into latches

**Block Diagram** (positive logic)



Absolute Maximum Ratings (Note 1)				Recommended Operating Conditions				
(Note 2)								
Supply Voltage ( $V_{CC}$ )		-0.5 to +7.0V		Supply Voltage ( $V_{CC}$ )	Min	Max	Units	
DC Input Voltage ( $V_{IN}$ )		-1.5 to $V_{CC}+1.5V$		DC Input or Output Voltage	2	6	V	
DC Output Voltage ( $V_{OUT}$ )		-0.5 to $V_{CC}+0.5V$		( $V_{IN}, V_{OUT}$ )	0	$V_{CC}$	V	
Clamp Diode Current ( $I_{IK}, I_{OK}$ )		$\pm 20$ mA		Operating Temperature Range ( $T_A$ )	-40	+85	$^{\circ}C$	
DC Output Current, per pin ( $I_{OUT}$ )		$\pm 25$ mA		Input Rise or Fall Times				
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )		$\pm 50$ mA		( $t_r, t_f$ ) $V_{CC} = 2.0V$		1000	ns	
Storage Temperature Range ( $T_{STG}$ )		-65 $^{\circ}C$ to +150 $^{\circ}C$		$V_{CC} = 4.5V$		500	ns	
Power Dissipation ( $P_D$ )				$V_{CC} = 6.0V$		400	ns	
(Note 3)		600 mW		<b>Note 1:</b> Absolute Maximum Ratings are those values beyond which damage to the device may occur.				
S.O. Package only		500 mW		<b>Note 2:</b> Unless otherwise specified all voltages are referenced to ground.				
Lead Temperature ( $T_L$ )				<b>Note 3:</b> Power Dissipation temperature derating — plastic "N" package: -12 mW/ $^{\circ}C$ from 65 $^{\circ}C$ to 85 $^{\circ}C$ .				
(Soldering 10 seconds)		260 $^{\circ}C$						
DC Electrical Characteristics (Note 4)								
Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^{\circ}C$			Units	
				Typ	Guaranteed Limits			
$V_{IH}$	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
$V_{IL}$	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
$V_{OH}$	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 6.0$ mA $ I_{OUT}  \leq 7.8$ mA	4.5V		3.98	3.84	3.7	V
			6.0V		5.48	5.34	5.2	V
$V_{OL}$	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 6.0$ mA $ I_{OUT}  \leq 7.8$ mA	4.5V		0.26	0.33	0.4	V
			6.0V		0.26	0.33	0.4	V
$I_{IN}$	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu A$
$I_{CC}$	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	$\mu A$
$I_{OZ}$	Maximum 3-STATE Leakage Current	Output in High Impedance State $V_{IN} = V_{IL}$ or $V_{IH}$ $V_{OUT} = V_{CC}$ or GND $\overline{OE} = V_{IH}$	6.0V		$\pm 0.5$	$\pm 5.0$	$\pm 10.0$	$\mu A$
<b>Note 4:</b> For a power supply of 5V $\pm 10\%$ the worst case output voltages ( $V_{OH}$ , and $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case $V_{IH}$ and $V_{IL}$ occur at $V_{CC}=5.5V$ and 4.5V respectively. (The $V_{IH}$ value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ , $I_{CC}$ , and $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.								

## AC Electrical Characteristics

$V_{CC} = 5V$ ,  $T_A = 25^\circ C$ ,  $C_L = 15\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
$f_{MAX}$	Maximum Operating Frequency for SCK		50	30	MHz
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from SCK to $Q_H$			30	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from $\overline{SLOAD}$ to $Q_H$			30	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from LCK to $Q_H$	$\overline{SLOAD} = \text{logic "0"}$	25	45	ns
$t_{PZH}$ , $t_{PZL}$	Output Enable Time	$R_L = 1\text{ k}\Omega$	18	28	ns
$t_{PHZ}$ , $t_{PLZ}$	Output Disable Time	$R_L = 1\text{ k}\Omega$ , $C_L = 5\text{ pF}$	19	25	ns
$t_S$	Minimum Setup Time from RCK to SCK		10	20	ns
$t_S$	Minimum Setup Time from SER to SCK		10	20	ns
$t_S$	Minimum Setup Time from Inputs A thru H to RCK		10	20	ns
$t_H$	Minimum Hold Time		0	5	ns
$t_W$	Minimum Pulse Width SCK, RCK, $\overline{SLOAD}$		8	16	ns

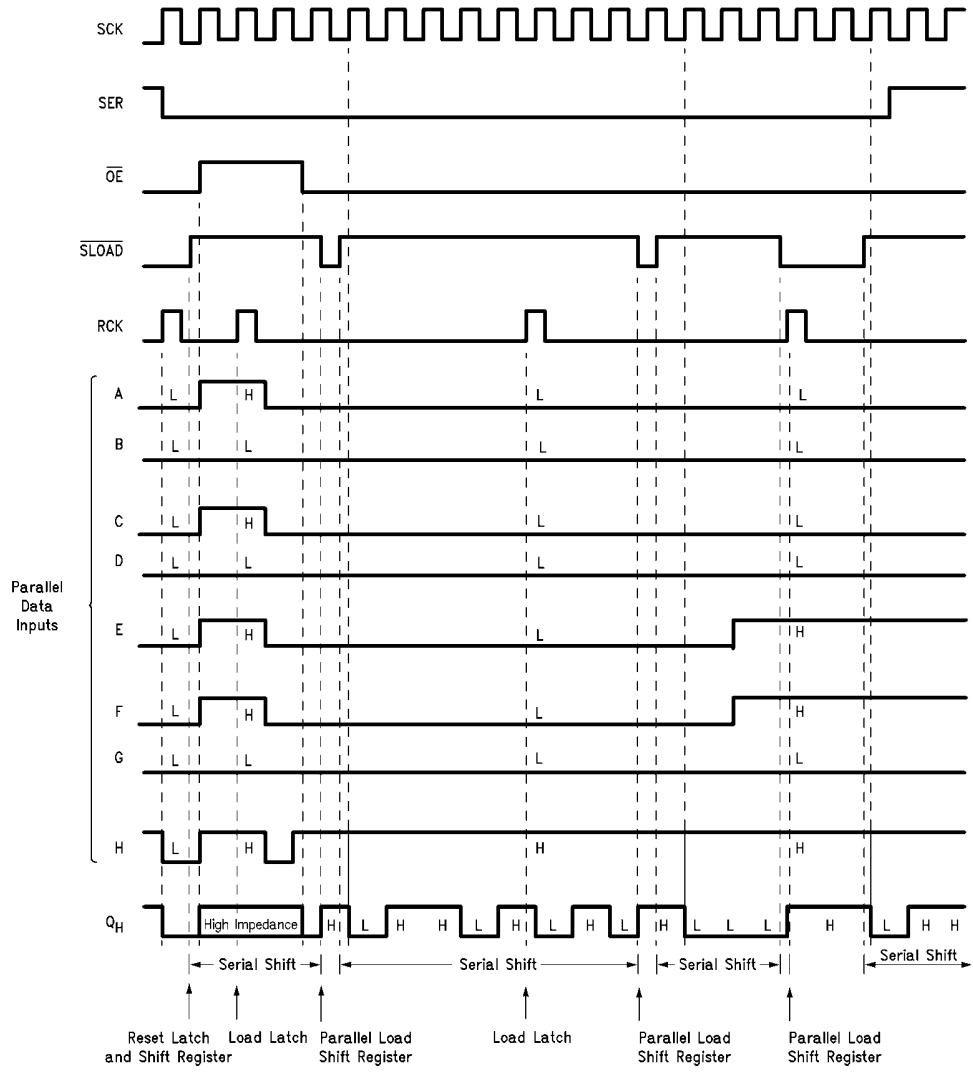
## AC Electrical Characteristics

$V_{CC} = 2.0\text{--}6V$ ,  $C_L = 50\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$  (unless otherwise specified)

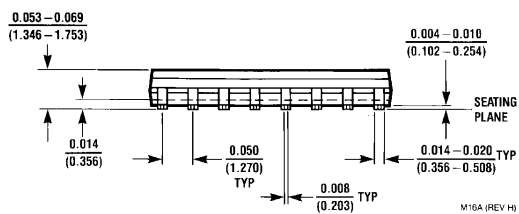
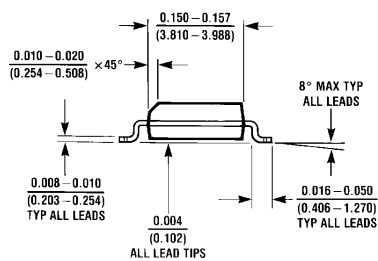
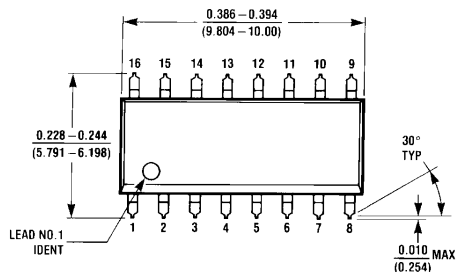
Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$			Units	
				Typ	Guaranteed Limits			
$f_{MAX}$	Maximum Operating Frequency for SCK		2.0V	6	4.8	4	MHz	
			4.5V	30	24	20	MHz	
			6.0V	35	28	24	MHz	
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from SCK or $\overline{SLOAD}$ to $Q_H$		2.0V	62	175	220	265	ns
			4.5V	20	35	44	53	ns
			6.0V	18	30	37	45	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from SCK or $\overline{SLOAD}$ to $Q_H$	$C_L = 150\text{ pF}$	2.0V	120	225	280	340	ns
			4.5V	31	45	56	68	ns
			6.0V	28	38	48	58	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay from RCK to $Q_H$		2.0V	80	210	265	315	ns
			4.5V	25	42	53	63	ns
			6.0V	21	36	45	54	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay RCK to $Q_H$	$C_L = 150\text{ pF}$	2.0V	80	210	265	313	ns
			4.5V	25	52	66	77	ns
			6.0V	21	44	56	66	ns
$t_{PZH}$ , $t_{PZL}$	Output Enable Time	$R_L = 1\text{ k}\Omega$	2.0V	70	150	189	224	ns
			4.5V	22	30	38	45	ns
			6.0V	20	26	32	38	ns
$t_{PHZ}$ , $t_{PLZ}$	Output Disable Time	$R_L = 1\text{ k}\Omega$	2.0V	70	150	189	224	ns
			4.5V	22	30	38	45	ns
			6.0V	20	26	32	38	ns
$t_S$	Minimum Setup Time from RCK to SCK		2.0V		100	125	150	ns
			4.5V		20	25	30	ns
			6.0V		17	22	25	ns
$t_S$	Minimum Setup Time from SER to SCK		2.0V		100	125	150	ns
			4.5V		20	25	30	ns
			6.0V		17	22	25	ns
$t_S$	Minimum Setup Time from Inputs A thru H to RCK		2.0V		100	125	150	ns
			4.5V		20	25	30	ns
			6.0V		17	22	25	ns
$t_H$	Minimum Hold Time		2.0V	-5	5	5	5	ns
			4.5V	0	5	5	5	ns
			6.0V	1	5	5	5	ns
$t_W$	Minimum Pulse Width SCK, RCK, $\overline{SLOAD}$ , $\overline{SLOAD}$		2.0V	30	80	100	120	ns
			4.5V	9	16	20	24	ns
			6.0V	8	14	17	20	ns

AC Electrical Characteristics (Continued)								
Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C	T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units	
				Typ	Guaranteed Limits			
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Time, Clock		2.0V		1500	1500	1500	ns
			4.5V		500	500	500	ns
			6.0V		400	400	400	ns
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise and Fall Time		2.0V	25	60	75	90	ns
			4.5V	6	12	15	18	ns
			6.0V	5	10	12	15	ns
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)			87				pF
C <sub>IN</sub>	Maximum Input Capacitance			5	10	10	10	pF
C <sub>OUT</sub>	Maximum Output Capacitance			15	20	20	20	pF
<p><b>Note 5:</b> C<sub>PD</sub> determines the no load dynamic power consumption, <math>P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}</math>, and the no load dynamic current consumption, <math>I_S = C_{PD} V_{CC} sf + I_{CC}</math>.</p>								

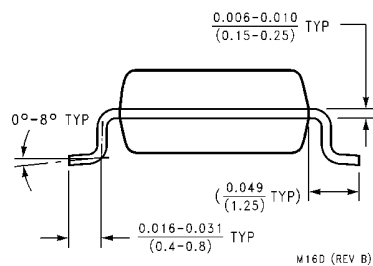
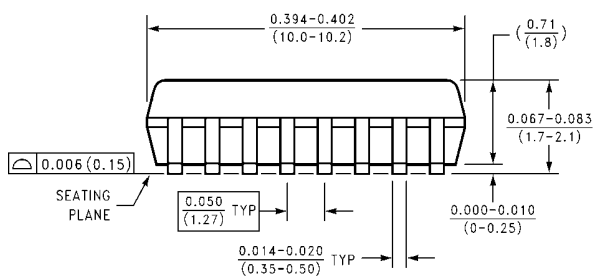
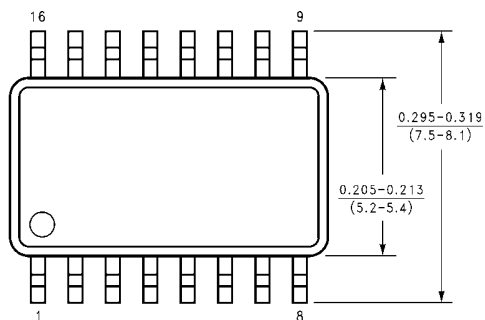
Timing Diagram



**Physical Dimensions** inches (millimeters) unless otherwise noted

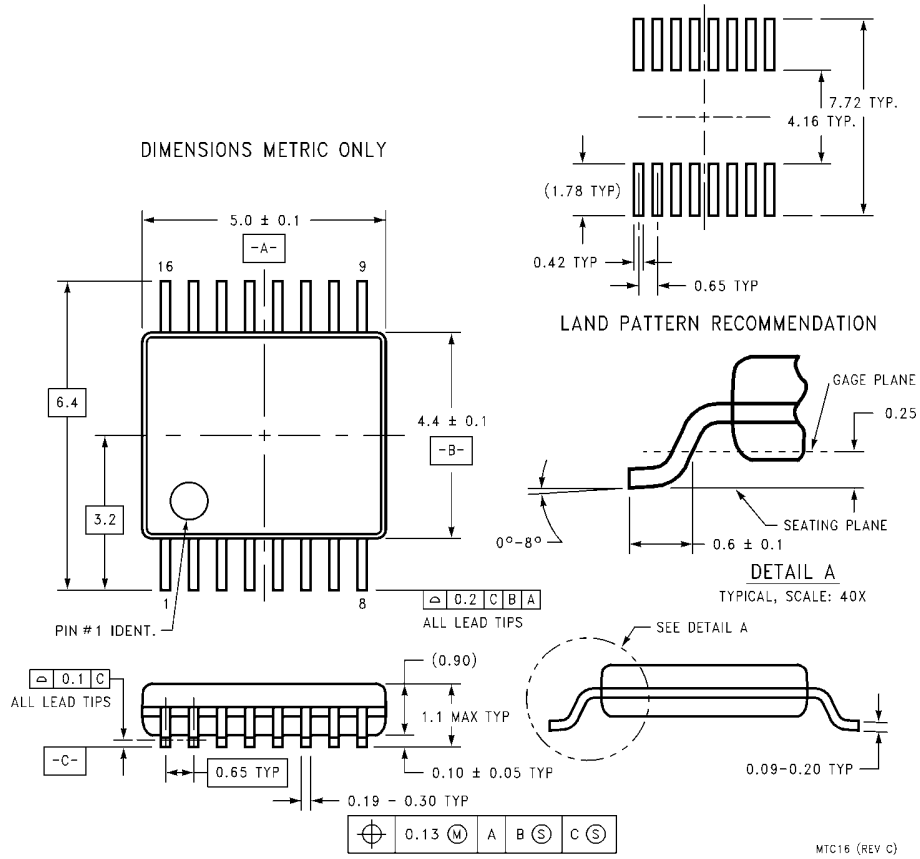


**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow  
Package Number M16A**



**16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M16D**

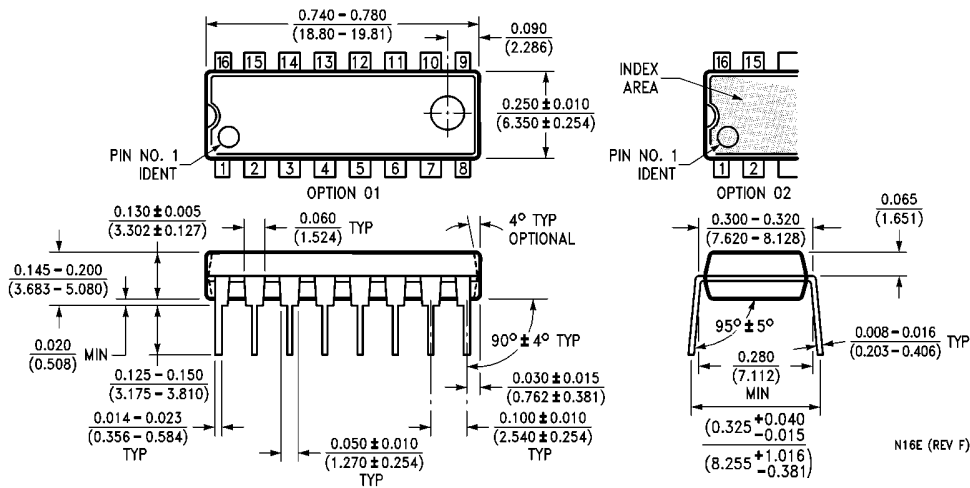
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16**



**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N16E**

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